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Components and Packaging for Laser Systems X

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Contents

v *Conference Committee*

COMPONENTS FOR LASER BEAM COMBINING AND FIBER BUNDLES

- 12866 02 **High-power triple clad fiber combiner and its application for the power scaling of 2.1 μm Ho³⁺-doped fiber lasers pumped at 1.9 μm** [12866-2]
- 12866 03 **Cutting-edge fused end fiber bundle technology for multi kW range applications** [12866-3]
- 12866 04 **S² mode content measurement of a 7+1 to 1 backward pump-signal combiner** [12866-4]
- 12866 05 **(6+1)x1 taper-fused side pump and signal combiner for kW-class fiber laser applications** [12866-5]

HIGH POWER/ENERGY LASER COMPONENTS

- 12866 06 **Optimizing fiber component manufacturing by observing the modal composition and PER in real-time** [12866-10]
- 12866 07 **Novel fiber optic components for high efficiency fiber amplifiers** [12866-11]
- 12866 08 **New wide range spectral data on the stress optical coefficient of optical glass** [12866-12]
- 12866 09 **High efficiency active air cooled (AAC) 12kw fiber laser system** [12866-13]

TECHNOLOGIES FOR ASSEMBLY, PACKAGING, AND RELIABILITY

- 12866 0A **Soldering of optics for the 532 nm, 100 mW raman laser for JAXA's mission to Phobos, and for ExoMars** [12866-15]
- 12866 0B **Comparison among illumination options for SWIR sensors** [12866-17]
- 12866 0C **Experimental research on discharge characteristics and laser pump performance of electrodeless micro xenon lamp** [12866-18]

LASER DIODE PACKAGING

- 12866 0D **Wavelength stabilized external cavity diode laser at 461 nm in hermetic 14-pin butterfly package (Invited Paper) [12866-25]**
- 12866 0E **High uniformity and high peak power 808nm QCW laser diode arrays [12866-28]**
- 12866 0F **Micro channel cooled single emitter housing [12866-29]**

SEMICONDUCTOR LIGHT SOURCES

- 12866 0G **Miniaturized external-cavity diode laser and tapered amplifier in hermetic 14-pin butterfly [12866-32]**
- 12866 0H **Hybrid semiconductor master-oscillator power-amplifiers with more than 5 W optical output power [12866-33]**

POSTER SESSION

- 12866 0I **Measurement of the spatiotemporal couplings induced by optical elements [12866-34]**
- 12866 0J **Diffraction grating microfabrication by ICP technique with two-layer lift-off processing in single crystal diamond [12866-35]**